

U.S. Serial No.: 10/560,941
Docket No.: 26281-13A

Examiner: G. E. Webb
Art Unit: 1796

RECEIVED
CENTRAL FAX CENTER

MAR 31 2008

LISTING OF CLAIMS

Claims 1-8. (Canceled)

9. (Original) A method for cleaning the solder flux comprising:

a step in which an object to be cleaned to which a solder flux is attached is cleaned using a cleaning agent for removing the solder flux which sets a content of benzyl alcohol to a value which falls within a range of 70 to 99.9 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of a glycol compound is below 1 weight% with respect to a total amount of the cleaning agent for removing the solder flux, and sets a content of benzyl alcohol to a value which falls within a range of 15 to 99 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of the glycol compound falls within a range of 1 to 40 weight% with respect to the total amount of the cleaning agent for removing the solder flux; and

a rinsing step which rinses the object to be cleaned using an alcoholic solvent.

10. (Original) The method for cleaning the solder flux according to claim 9, wherein the concentration of benzyl alcohol in the rinse solution in the rinsing step is set to 30 weight% or less.

11. (Previously Presented) The method for cleaning the solder flux according to claim 9, wherein the solder flux is either a lead-free solder flux or a high-melting-point solder flux containing rosin as a main component.

12. (Previously Presented) The method for cleaning the solder flux according to claim 9, wherein an object to be cleaned to which the solder flux is adhered is cleaned under conditions of 10 to 90 °C and 0.5 to 30 minutes using a cleaning agent for removing the solder flux.